



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I ² C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	86
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32lg280f64-qfp100t

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (°C)	Package
EFM32LG395F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG840F64G-E-QFN64	64	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG840F128G-E-QFN64	128	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG840F256G-E-QFN64	256	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG842F64G-E-QFP64	64	32	48	1.98 - 3.8	-40 - 85	TQFP64
EFM32LG842F128G-E-QFP64	128	32	48	1.98 - 3.8	-40 - 85	TQFP64
EFM32LG842F256G-E-QFP64	256	32	48	1.98 - 3.8	-40 - 85	TQFP64
EFM32LG880F64G-E-QFP100	64	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG880F128G-E-QFP100	128	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG880F256G-E-QFP100	256	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG890F64G-E-BGA112	64	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG890F128G-E-BGA112	128	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG890F256G-E-BGA112	256	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG895F64G-E-BGA120	64	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG895F128G-E-BGA120	128	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG895F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG900F256G-E-D1I	256	32	48	1.98 - 3.8	-40 - 85	Wafer
EFM32LG940F64G-E-QFN64	64	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG940F128G-E-QFN64	128	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG940F256G-E-QFN64	256	32	48	1.98 - 3.8	-40 - 85	QFN64
EFM32LG942F64G-E-BGA120	64	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG942F128G-E-BGA120	128	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG942F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG980F64G-E-QFP100	64	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG980F128G-E-QFP100	128	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG980F256G-E-QFP100	256	32	48	1.98 - 3.8	-40 - 85	LQFP100
EFM32LG990F64G-E-BGA112	64	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG990F128G-E-BGA112	128	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG990F256G-E-BGA112	256	32	48	1.98 - 3.8	-40 - 85	BGA112
EFM32LG995F64G-E-BGA120	64	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG995F128G-E-BGA120	128	32	48	1.98 - 3.8	-40 - 85	BGA120
EFM32LG995F256G-E-BGA120	256	32	48	1.98 - 3.8	-40 - 85	BGA120

Module	Configuration	Pin Connections
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0], DAC0_OUTxALT
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	83 pins	Available pins are shown in 5.9.3 GPIO Pinout Overview

3.2.15 EFM32LG890

The features of the EFM32LG890 is a subset of the feature set described in the EFM32LG Reference Manual. The following table describes device specific implementation of the features.

Table 3.15. EFM32LG890 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
EBI	Full configuration	EBI_A[27:0], EBI_AD[15:0], EBI_ARDY, EBI_ALE, EBI_BL[1:0], EBI_CS[3:0], EBI_CSTFT, EBI_DCLK, EBI_DTEN, EBI_HSNCR, EBI_NANDREN, EBI_NANDWEN, EBI_REn, EBI_VSNCR, EBI_WEn
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
I2C1	Full configuration	I2C1_SDA, I2C1_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	Full configuration with I2S	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration with I2S	US2_TX, US2_RX, US2_CLK, US2_CS
UART0	Full configuration	U0_TX, U0_RX
UART1	Full configuration	U1_TX, U1_RX
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
TIMER3	Full configuration	TIM3_CC[2:0]
RTC	Full configuration	NA
BURTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O

4.9 Oscillators

4.9.1 LFXO

Table 4.8. LFXO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supported nominal crystal frequency	f_{LFXO}		—	32.768	—	kHz
Supported crystal equivalent series resistance (ESR)	ESR_{LFXO}		—	30	120	k Ω
Supported crystal external load range	C_{LFXOL}		X ¹	—	25	pF
Current consumption for core and buffer after startup.	I_{LFXO}	ESR=30 k Ω , C_L =10 pF, LFXOBOOST in CMU_CTRL is 1	—	190	—	nA
Start- up time.	t_{LFXO}	ESR=30 k Ω , C_L =10 pF, 40% - 60% duty cycle has been reached, LFXO-BOOST in CMU_CTRL is 1	—	400	—	ms
Note: 1. See Minimum Load Capacitance (C_{LFXOL}) Requirement For Safe Crystal Startup in Configurator in Simplicity Studio.						

For safe startup of a given crystal, the Configurator tool in Simplicity Studio contains a tool to help users configure both load capacitance and software settings for using the LFXO. For details regarding the crystal configuration, the reader is referred to application note *AN0016 EFM32 Oscillator Design Consideration*.

4.9.2 HFXO

Table 4.9. HFXO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supported nominal crystal Frequency	f_{HFXO}		4	—	48	MHz
Supported crystal equivalent series resistance (ESR)	ESR_{HFXO}	Crystal frequency 48 MHz	—	—	50	Ω
		Crystal frequency 32 MHz	—	30	60	Ω
		Crystal frequency 4 MHz	—	400	1500	Ω
The transconductance of the HFXO input transistor at crystal startup	g_{mHFXO}	HFXOBOOST in CMU_CTRL equals 0b11	20	—	—	mS
Supported crystal external load range	C_{HFXOL}		5	—	25	pF
Current consumption for HFXO after startup	I_{HFXO}	4 MHz: ESR=400 Ω , C_L =20 pF, HFXO-BOOST in CMU_CTRL equals 0b11	—	85	—	μA
		32 MHz: ESR=30 Ω , C_L =10 pF, HFXO-BOOST in CMU_CTRL equals 0b11	—	165	—	μA
Startup time	t_{HFXO}	32 MHz: ESR=30 Ω , C_L =10 pF, HFXO-BOOST in CMU_CTRL equals 0b11	—	400	—	μs

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Gain Bandwidth Product	GBW _{OPAMP}	(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 0.3 V	—	0.393 ¹	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 1 V	—	0.487 ¹	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 2 V	—	0.392 ¹	—	MHz
		(OPA0)BIASPROG=0x0,(OPA0)HALF-BIAS=0x1, DC bias = 2.7 V	—	0.318 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 0.3 V	—	1.595 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 1 V	—	2.661 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 2 V	—	2.566 ¹	—	MHz
		(OPA0)BIASPROG=0x4,(OPA0)HALF-BIAS=0x1, DC bias = 2.7 V	—	1.787 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 0.3 V	—	0.460 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 1 V	—	0.447 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 2 V	—	0.372 ¹	—	MHz
		(OPA1)BIASPROG=0x0,(OPA1)HALF-BIAS=0x1, DC bias = 2.7 V	—	0.295 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 0.3 V	—	1.890 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 1 V	—	2.849 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 2 V	—	2.561 ¹	—	MHz
		(OPA1)BIASPROG=0x4,(OPA1)HALF-BIAS=0x1, DC bias = 2.7 V	—	1.705 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 0.3 V	—	0.339 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 1 V	—	0.432 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 2 V	—	0.347 ¹	—	MHz
		(OPA2)BIASPROG=0x0,(OPA2)HALF-BIAS=0x1, DC bias = 2.7 V	—	0.286 ¹	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, DC bias = 0.3 V	—	1.271 ¹	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, DC bias = 1 V	—	1.429 ¹	—	MHz
		(OPA2)BIASPROG=0x4,(OPA2)HALF-BIAS=0x1, DC bias = 2 V	—	1.283 ¹	—	MHz

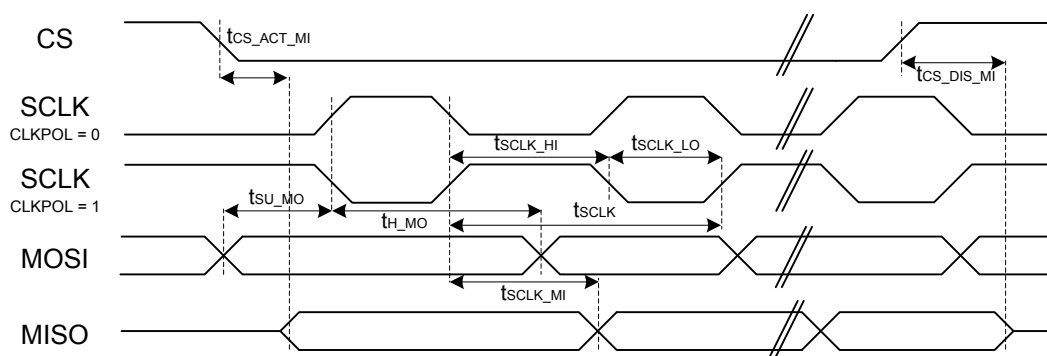


Figure 4.43. SPI Master Timing

Table 4.30. SPI Slave Timing

Parameter	Symbol	Min	Typ	Max	Unit
SCKL period	$t_{SCLK_sl}^{1\ 2}$	$6 \times t_{HFERCLK}$	—	—	ns
SCLK high period	$t_{SCLK_hi}^{1\ 2}$	$3 \times t_{HFERCLK}$	—	—	ns
SCLK low period	$t_{SCLK_lo}^{1\ 2}$	$3 \times t_{HFERCLK}$	—	—	ns
CS active to MISO	$t_{CS_ACT_MI}^{1\ 2}$	5.00	—	35.00	ns
CS disable to MISO high-impedance	$t_{CS_DIS_MI}^{1\ 2}$	5.00	—	35.00	ns
MOSI setup time	$t_{SU_MO}^{1\ 2}$	5.00	—	—	ns
MOSI hold time	$t_{H_MO}^{1\ 2}$	$2 + 2 \times t_{HFERCLK}$	—	—	ns
SCLK to MISO	$t_{SCLK_MI}^{1\ 2}$	$7 + t_{HFERCLK}$	—	$42 + 2 \times t_{HFERCLK}$	ns

Note:

1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0)
2. Measurement done at 10% and 90% of V_{DD} (figure shows 50% of V_{DD})

Table 4.31. SPI Slave Timing with SSSEARLY and SMSDELAY

Parameter	Symbol	Min	Typ	Max	Unit
SCKL period	$t_{SCLK_sl}^{1\ 2}$	$6 \times t_{HFERCLK}$	—	—	ns
SCLK high period	$t_{SCLK_hi}^{1\ 2}$	$3 \times t_{HFERCLK}$	—	—	ns
SCLK low period	$t_{SCLK_lo}^{1\ 2}$	$3 \times t_{HFERCLK}$	—	—	ns
CS active to MISO	$t_{CS_ACT_MI}^{1\ 2}$	5.00	—	35.00	ns
CS disable to MISO	$t_{CS_DIS_MI}^{1\ 2}$	5.00	—	35.00	ns
MOSI setup time	$t_{SU_MO}^{1\ 2}$	5.00	—	—	ns
MOSI hold time	$t_{H_MO}^{1\ 2}$	$2 + 2 \times t_{HFERCLK}$	—	—	ns

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
3	PA2		EBI_AD11 #0/1/2	TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TD0 #3
4	PA3		EBI_AD12 #0/1/2	TIM0_CDTI0 #0	U0_TX #2	LES_ALTEX2 #0 ETM_TD1 #3
5	PA4		EBI_AD13 #0/1/2	TIM0_CDTI1 #0	U0_RX #2	LES_ALTEX3 #0 ETM_TD2 #3
6	PA5		EBI_AD14 #0/1/2	TIM0_CDTI2 #0	LEU1_TX #1	LES_ALTEX4 #0 ETM_TD3 #3
7	PA6		EBI_AD15 #0/1/2		LEU1_RX #1	ETM_TCLK #3 GPIO_EM4WU1
8	IOVDD_0	Digital IO power supply 0.				
9	PB0		EBI_A16 #0/1/2	TIM1_CC0 #2		
10	PB1		EBI_A17 #0/1/2	TIM1_CC1 #2		
11	PB2		EBI_A18 #0/1/2	TIM1_CC2 #2		
12	PB3		EBI_A19 #0/1/2	PCNT1_S0IN #1	US2_TX #1	
13	PB4		EBI_A20 #0/1/2	PCNT1_S1IN #1	US2_RX #1	
14	PB5		EBI_A21 #0/1/2		US2_CLK #1	
15	PB6		EBI_A22 #0/1/2		US2_CS #1	
16	VSS	Ground.				
17	IOVDD_1	Digital IO power supply 1.				
18	PC0	ACMP0_CH0 DAC0_OUT0ALT #0/ OPAMP_OUT0ALT	EBI_A23 #0/1/2	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5 US1_TX #0 I2C0_SDA #4	LES_CH0 #0 PRS_CH2 #0
19	PC1	ACMP0_CH1 DAC0_OUT0ALT #1/ OPAMP_OUT0ALT	EBI_A24 #0/1/2	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5 US1_RX #0 I2C0_SCL #4	LES_CH1 #0 PRS_CH3 #0
20	PC2	ACMP0_CH2 DAC0_OUT0ALT #2/ OPAMP_OUT0ALT	EBI_A25 #0/1/2	TIM0_CDTI0 #4	US2_TX #0	LES_CH2 #0
21	PC3	ACMP0_CH3 DAC0_OUT0ALT #3/ OPAMP_OUT0ALT	EBI_NANDREn #0/1/2	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0
22	PC4	ACMP0_CH4 OPAMP_P0	EBI_A26 #0/1/2	TIM0_CDTI2 #4 LE- TIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
23	PC5	ACMP0_CH5 OPAMP_N0	EBI_NANDWEn #0/1/2	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
24	PB7	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
25	PB8	LFXTAL_N		TIM1_CC1 #3	US0_RX #4 US1_CS #0	

5.5 EFM32LG295 (BGA120)

5.5.1 Pinout

The EFM32LG295 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

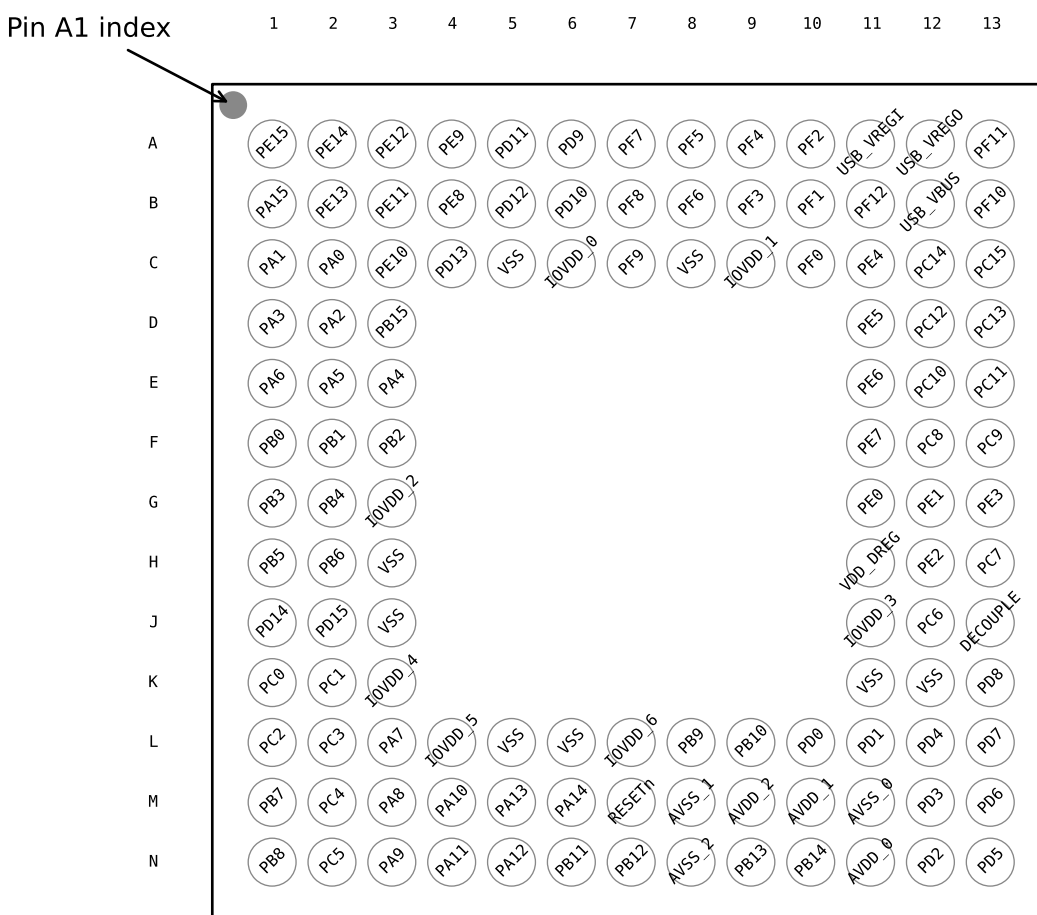


Figure 5.9. EFM32LG295 Pinout (top view, not to scale)

Table 5.13. Device Pinout

BGA120 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
A1	PE15		EBI_AD07 #0/1/2	TIM3_CC1 #0	LEU0_RX #2	
A2	PE14		EBI_AD06 #0/1/2	TIM3_CC0 #0	LEU0_TX #2	

5.7.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.20. Alternate functionality overview

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5							Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6							Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7							Analog comparator ACMP0, channel 7.
ACMP0_O	PE13		PD6					Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8							Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9							Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10							Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11							Analog comparator ACMP1, channel 3.
ACMP1_O	PF2		PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2							Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3							Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_VIN	PD8							Battery input for Backup Power Domain

5.9 EFM32LG380 (LQFP100)

5.9.1 Pinout

The EFM32LG380 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

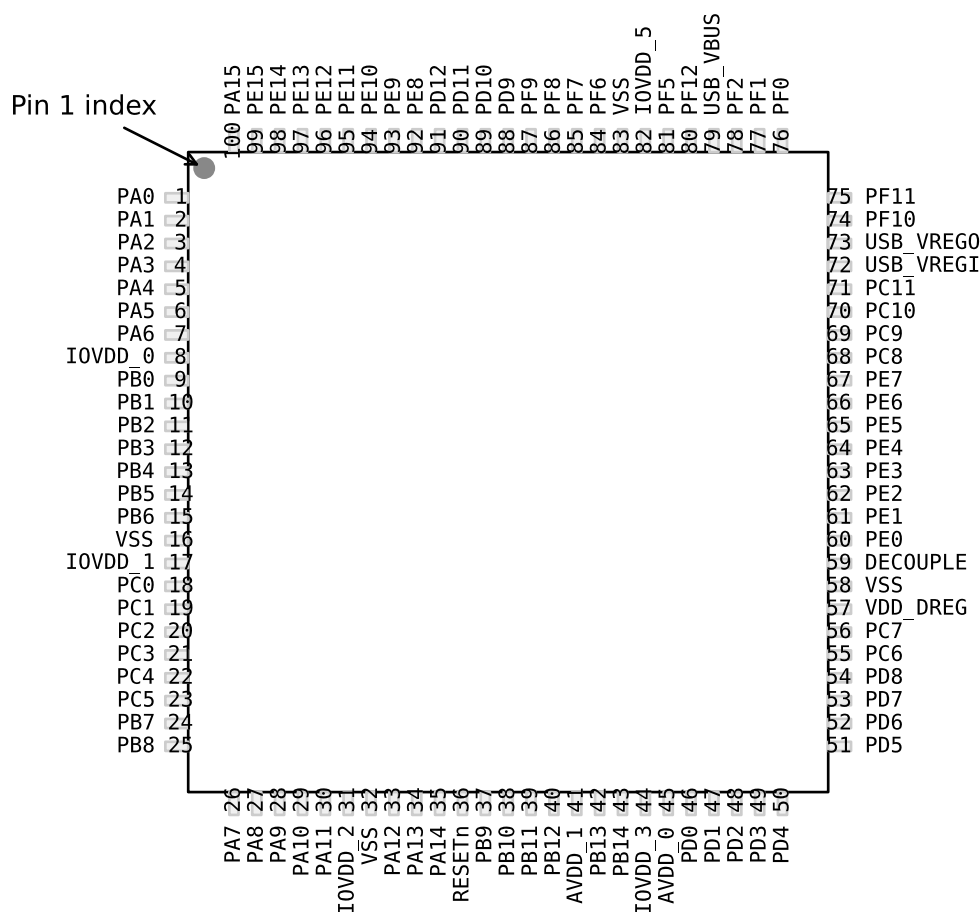


Figure 5.17. EFM32LG380 Pinout (top view, not to scale)

Table 5.25. Device Pinout

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
1	PA0		EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
2	PA1		EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
L10	AVDD_0	Analog power supply 0.				
L11	PD0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	

BGA120 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
F11	PE7		EBI_A14 #0/1/2		US0_TX #1	
F12	PC8	ACMP1_CH0	EBI_A15 #0/1/2	TIM2_CC0 #2	US0_CS #2	LES_CH8 #0
F13	PC9	ACMP1_CH1	EBI_A09 #1/2	TIM2_CC1 #2	US0_CLK #2	LES_CH9 #0 GPIO_EM4WU2
G1	PB3		EBI_A19 #0/1/2	PCNT1_S0IN #1	US2_TX #1	
G2	PB4		EBI_A20 #0/1/2	PCNT1_S1IN #1	US2_RX #1	
G3	IOVDD_2	Digital IO power supply 2.				
G11	PE0		EBI_A07 #0/1/2	TIM3_CC0 #1 PCNT0_S0IN #1	U0_TX #1 I2C1_SDA #2	
G12	PE1		EBI_A08 #0/1/2	TIM3_CC1 #1 PCNT0_S1IN #1	U0_RX #1 I2C1_SCL #2	
G13	PE3	BU_STAT	EBI_A10 #0		U1_RX #3	ACMP1_O #1
H1	PB5		EBI_A21 #0/1/2		US2_CLK #1	
H2	PB6		EBI_A22 #0/1/2		US2_CS #1	
H3	VSS	Ground.				
H11	VDD_DREG	Power supply for on-chip voltage regulator.				
H12	PE2	BU_VOUT	EBI_A09 #0	TIM3_CC2 #1	U1_TX #3	ACMP0_O #1
H13	PC7	ACMP0_CH7	EBI_A06 #0/1/2		LEU1_RX #0 I2C0_SCL #2	LES_CH7 #0 ETM_TD0 #2
J1	PD14				I2C0_SDA #3	
J2	PD15				I2C0_SCL #3	
J3	VSS	Ground.				
J11	IOVDD_3	Digital IO power supply 3.				
J12	PC6	ACMP0_CH6	EBI_A05 #0/1/2		LEU1_TX #0 I2C0_SDA #2	LES_CH6 #0 ETM_TCLK #2
J13	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size C _{DECOUPLE} is required at this pin.				
K1	PC0	ACMP0_CH0 DAC0_OUT0ALT #0/ OPAMP_OUT0ALT	EBI_A23 #0/1/2	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5 US1_TX #0 I2C0_SDA #4	LES_CH0 #0 PRS_CH2 #0
K2	PC1	ACMP0_CH1 DAC0_OUT0ALT #1/ OPAMP_OUT0ALT	EBI_A24 #0/1/2	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5 US1_RX #0 I2C0_SCL #4	LES_CH1 #0 PRS_CH3 #0
K3	IOVDD_4	Digital IO power supply 4.				
K11	VSS	Ground.				
K12	VSS	Ground.				
K13	PD8	BU_VIN				CMU_CLK1 #1

5.14 EFM32LG880 (LQFP100)

5.14.1 Pinout

The EFM32LG880 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

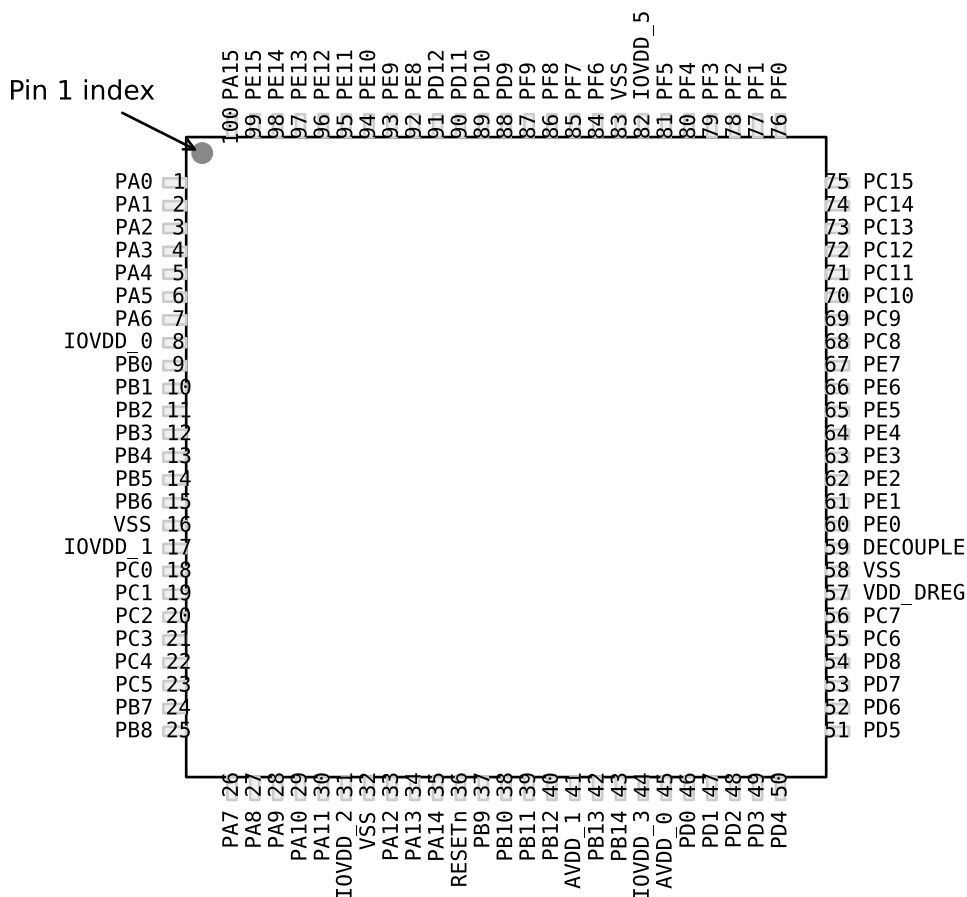


Figure 5.27. EFM32LG880 Pinout (top view, not to scale)

Table 5.40. Device Pinout

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
1	PA0	LCD_SEG13	EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
2	PA1	LCD_SEG14	EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0

5.17.2 Alternate Functionality Padout

A wide selection of alternate functionality is available for multiplexing to various pads. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the padout is shown in the column corresponding to LOCATION 0.

Table 5.50. Alternate functionality overview

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5							Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6							Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7							Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2	PD6					Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8							Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9							Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10							Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11							Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12							Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13							Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14							Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15							Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3	PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2							Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3							Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.

QFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
3	PA2	LCD_SEG15	TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TD0 #3
4	PA3	LCD_SEG16	TIM0_CDTI0 #0		LES_ALTEX2 #0 ETM_TD1 #3
5	PA4	LCD_SEG17	TIM0_CDTI1 #0		LES_ALTEX3 #0 ETM_TD2 #3
6	PA5	LCD_SEG18	TIM0_CDTI2 #0	LEU1_TX #1	LES_ALTEX4 #0 ETM_TD3 #3
7	IOVDD_0	Digital IO power supply 0.			
8	VSS	Ground.			
9	PB3	LCD_SEG20/ LCD_COM4	PCNT1_S0IN #1	US2_TX #1	
10	PB4	LCD_SEG21/ LCD_COM5	PCNT1_S1IN #1	US2_RX #1	
11	PB5	LCD_SEG22/ LCD_COM6		US2_CLK #1	
12	PB6	LCD_SEG23/ LCD_COM7		US2_CS #1	
13	PC4	ACMP0_CH4 OPAMP_P0	TIM0_CDTI2 #4 LE- TIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
14	PC5	ACMP0_CH5 OPAMP_N0	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0
15	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
16	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
17	PA12	LCD_BCAP_P	TIM2_CC0 #1		
18	PA13	LCD_BCAP_N	TIM2_CC1 #1		
19	PA14	LCD_BEXT	TIM2_CC2 #1		
20	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0 / OPAMP_OUT0	TIM1_CC2 #3 LE- TIM0_OUT0 #1	I2C1_SDA #1	
22	VSS	Ground.			
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
25	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			
27	AVDD_0	Analog power supply 0.			

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
F11	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size C _{DECOUPLE} is required at this pin.				
G1	PB5	LCD_SEG22/ LCD_COM6	EBI_A21 #0/1/2		US2_CLK #1	
G2	PB6	LCD_SEG23/ LCD_COM7	EBI_A22 #0/1/2		US2_CS #1	
G3	VSS	Ground.				
G4	IOVDD_0	Digital IO power supply 0.				
G8	IOVDD_4	Digital IO power supply 4.				
G9	VSS	Ground.				
G10	PC6	ACMP0_CH6	EBI_A05 #0/1/2		LEU1_TX #0 I2C0_SDA #2	LES_CH6 #0 ETM_TCLK #2
G11	PC7	ACMP0_CH7	EBI_A06 #0/1/2		LEU1_RX #0 I2C0_SCL #2	LES_CH7 #0 ETM_TD0 #2
H1	PC0	ACMP0_CH0 DAC0_OUT0ALT #0/ OPAMP_OUT0ALT	EBI_A23 #0/1/2	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5 US1_TX #0 I2C0_SDA #4	LES_CH0 #0 PRS_CH2 #0
H2	PC2	ACMP0_CH2 DAC0_OUT0ALT #2/ OPAMP_OUT0ALT	EBI_A25 #0/1/2	TIM0_CDTI0 #4	US2_TX #0	LES_CH2 #0
H3	PD14				I2C0_SDA #3	
H4	PA7	LCD_SEG35	EBI_CSTFT #0/1/2			
H5	PA8	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
H6	VSS	Ground.				
H7	IOVDD_3	Digital IO power supply 3.				
H8	PD8	BU_VIN				CMU_CLK1 #1
H9	PD5	ADC0_CH5 OPAMP_OUT2 #0			LEU0_RX #0	ETM_TD3 #0/2
H10	PD6	ADC0_CH6 OPAMP_P1		TIM1_CC0 #4 LE- TIM0_OUT0 #0 PCNT0_S0IN #3	US1_RX #2 I2C0_SDA #1	LES_ALTEX0 #0 ACMP0_O #2 ETM_TD0 #0
H11	PD7	ADC0_CH7 OPAMP_N1		TIM1_CC1 #4 LE- TIM0_OUT1 #0 PCNT0_S1IN #3	US1_TX #2 I2C0_SCL #1	CMU_CLK0 #2 LES_ALTEX1 #0 ACMP1_O #2 ETM_TCLK #0
J1	PC1	ACMP0_CH1 DAC0_OUT0ALT #1/ OPAMP_OUT0ALT	EBI_A24 #0/1/2	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5 US1_RX #0 I2C0_SCL #4	LES_CH1 #0 PRS_CH3 #0
J2	PC3	ACMP0_CH3 DAC0_OUT0ALT #3/ OPAMP_OUT0ALT	EBI_NANDREn #0/1/2	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2		PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0A LT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 /OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1A LT					PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2		PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.
EBI_A06	PC7	PC7	PC7					External Bus Interface (EBI) address output pin 06.
EBI_A07	PE0	PE0	PE0					External Bus Interface (EBI) address output pin 07.

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 /OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 / OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1ALT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15	PD1	PD2				Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.

8.3 CSP81 Package Marking

In the illustration below package fields and position are shown.

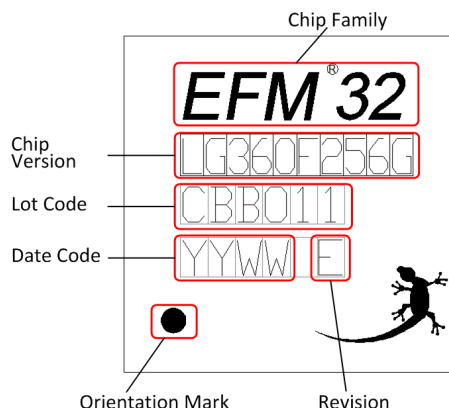


Figure 8.5. Example Chip Marking (Top View)

8.4 CSP81 Environmental

WLCSP devices can be handled and soldered using industry standard surface mount assembly techniques. However, because WLCSP devices are essentially a piece of silicon and are not encapsulated in plastic, they are susceptible to mechanical damage and may be sensitive to light. When WLCSPs must be used in an environment exposed to light, it may be necessary to cover the top and sides with an opaque material.

10.3 TQFP64 Package Marking

In the illustration below package fields and position are shown.

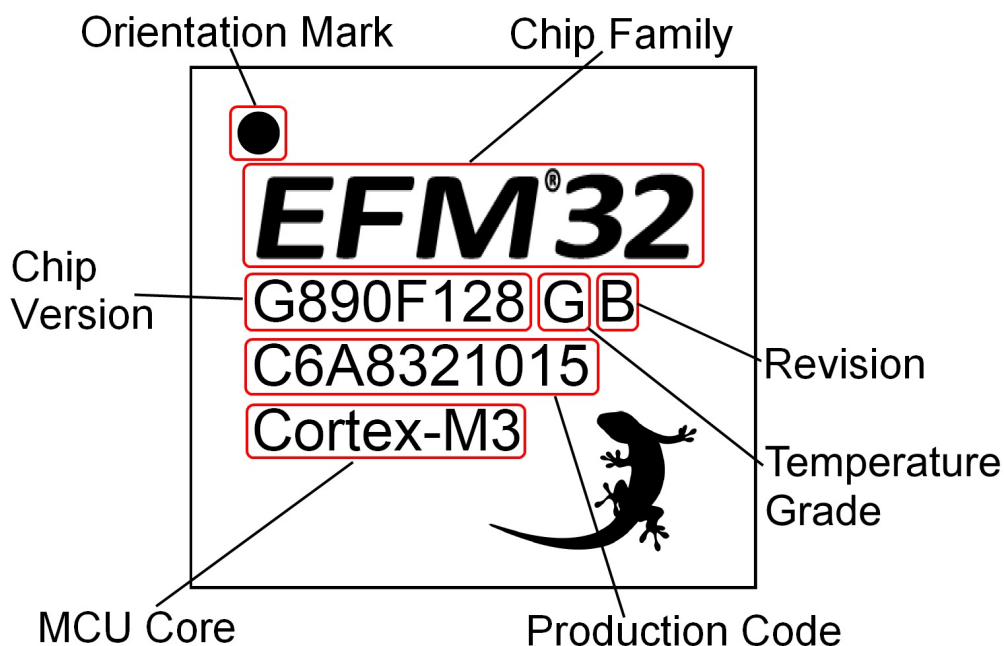


Figure 10.5. Example Chip Marking (Top View)